AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Claims 1-18 . (Canceled)

19. (Currently Amended) A method of fabricating a device, comprising:

fabricating an integrated circuit chip, the integrated circuit chip including

a plurality of electrical bond pads;

fabricating a substrate;

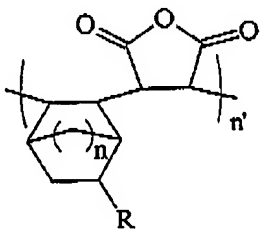
positioning the integrated circuit chip relative to the substrate;

providing electrical connection between the integrated circuit chip and the substrate during a reflow operation;

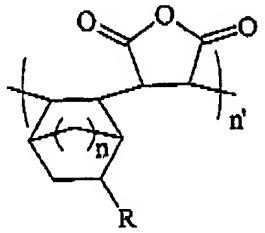
providing an underfill composition between the integrated circuit chip and the substrate, the underfill composition including

a resin; and

a curing agent selected from the group consisting of low molecular weight maleic anhydride polymers comprising cyclohexane or bridged cyclohexane having the following structural formula,



where n is 0, 2 or 3, n' is 5 to 50, and R is selected from the group consisting of alkyl, aryl, substituted aryls, esters, ethers, lactones, anhydrides, alcohols, nitriles, epoxy, carboxylic acids and mixtures thereof, maleic anhydride polymers comprising norbornene having the following structural formula:



where n is 1, n' is 5 to 50, and R is selected from the group consisting of ethers, lactones, anhydrides, alcohols, nitriles, epoxy, carboxylic acids, and ~~maleic~~ styrene/maleic anhydride polymers ~~comprising styrene~~ having a molecular weight of about 1600 g/mole, and mixtures thereof.

20. (Original) The method according to claim 19 wherein the underfill composition is provided simultaneously during reflow.

21. (Original) The method according to claim 19 wherein the underfill composition is provided after reflow.

22. (Original) The method according to claim 19 wherein the underfill composition is cured.

23. (Previously Presented) The method according to claim 22 wherein the curing occurs within a temperature range of from about 130° C to about 170° C.

24. (Previously Presented) The method according to claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.

25. (Canceled)